CD4511B Types

CMOS BCD-to-7-Segment Latch Decoder Drivers

High-Voltage Types (20-Volt Rating)

DISPLAY

0123456789   92CS-25087

BCD INPUTS   LT   7-SEGMENT OUTPUTS

A 7   B 1   C 2   D 6   LATCH   DECODER   DRIVER   13 g, 12 b, 11 c, 10 d, 9 e, 15 f, 14 g

LE/STROBE 5   BL

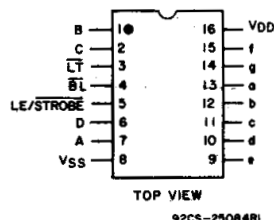Vss•8   VDD•16   92CS-25083R2

FUNCTIONAL DIAGRAM

■ CD4511B types are BCD-to-7-segment latch decoder drivers constructed with CMOS logic and n-p-n bipolar transistor output devices on a single monolithic structure. These devices combine the low quiescent power dissipation and high noise immunity features of RCA CMOS with n-p-n bipolar output transistors capable of sourcing up to 25 mA. This capability allows the CD4511B types to drive LED's and other displays directly.

Lamp Test (LT), Blanking (BL), and Latch Enable or Strobe inputs are provided to test the display, shut off or intensity-modulate it, and store or strobe a BCD code, respectively. Several different signals may be multiplexed and displayed when external multiplexing circuitry is used.

The CD4511B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).
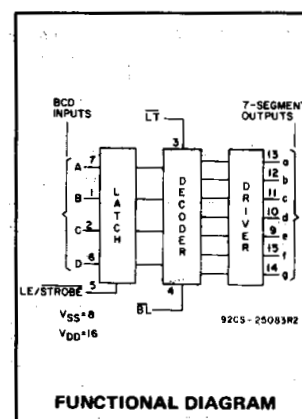
These devices are similar to the type MC14511.

Features:

■ High-output-sourcing capability . . . . up to 25 mA
■ Input latches for BCD Code storage
■ Lamp Test and Blanking capability
■ 7-segment outputs blanked for BCD input codes > 1001
■ 100% tested for quiescent current at 20 V
■ Max. input current of 1 μA at 18 V, over full package-temperature range, 100 nA at 18 V and 25°C
■ 5-V, 10-V, and 15-V parametric ratings

Applications:

■ Driving common-cathode LED displays
■ Multiplexing with common-cathode LED displays
■ Driving incandescent displays
■ Driving low-voltage fluorescent displays

B 1 ● / 16 VDD
C 2 / 15 f
LT 3 / 14 g
BL 4 / 13 a
LE/STROBE 5 / 12 b
D 6 / 11 c
A 7 / 10 d
Vss 8 / 9 e

TOP VIEW

92CS-25084RI

CD4511B TERMINAL ASSIGNMENT

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_DD)
  Voltages referenced to V_SS Terminal) . . . . −0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS . . . . −0.5V to V_DD +0.5V
DC INPUT CURRENT, ANY ONE INPUT . . . . ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
  For T_A = −55°C to +100°C 500mW
  For T_A = +100°C to +125°C . . . . Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
  FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) . . . . −55°C to +125°C
STORAGE TEMPERATURE RANGE (T_stg) . . . . −65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
  At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max . . . . +265°C

OPERATING CONDITIONS AT T_A = 25°C Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

Characteristic	V_DD	Min.	Max.	Units
Supply-Voltage Range (T_A): (Full Package-Temperature Range)	−	3	18	V
Set-Up Time (t_S)	5	150	−	ns
	10	70	−	ns
	15	40	−	ns
Hold Time (t_H)	5	0	−	ns
	10	0	−	ns
	15	0	−	ns
Strobe Pulse Width (t_W)	5	400	−	ns
	10	160	−	ns
	15	100	−	ns

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COMMERCIAL CMOS HIGH VOLTAGE ICs

CD4511B Types

STATIC ELECTRICAL CHARACTERISTICS

| CHARACTERISTIC	TEST CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)							Units
	I_{OH} (mA)	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	+25 Min.	+25 Typ.	+25 Max.	
Quiescent Device Current: I_{DD} Max.	−	−	−	5	5	5	150	150	−	0.04	5	µA
	−	−	−	10	10	10	300	300	−	0.04	10	
	−	−	−	15	20	20	600	600	−	0.04	20	
	−	−	−	20	100	100	3000	3000	−	0.08	100	
Output Voltage: Low-Level V_{OL} Max.	−	−	0,5	5	0.05				−	0	0.05	V
	−	−	0,10	10	0.05				−	0	0.05	
	−	−	0,15	15	0.05				−	0	0.05	
High-Level V_{OH} Min.	−	−	0,5	5	4	4	4.2	4.2	4.1	4.55	−	V
	−	−	0,10	10	9	9	9.2	9.2	9.1	9.55	−	
	−	−	0,15	15	14	14	14.2	14.2	14.1	14.55	−	
Input Low Voltage, V_{IL} Max.	−	0.5,3.8	−	5	1.5				−	−	1.5	V
	−	1,8.8	−	10	3				−	−	3	
	−	1.5,13.8	−	15	4				−	−	4	
Input High Voltage, V_{IH} Min.	−	0.5,3.8	−	5	3.5				3.5	−	−	V
	−	1,8.8	−	10	7				7	−	−	
	−	1.5,13.8	−	15	11				11	−	−	
Output Drive Voltage: High Level V_{OH} Min.	0			5	4.0	4.0	4.20	4.20	4.10	4.55	−	V
	5	−					−	−	−	4.25	−	
	10				3.80	3.80	3.90	3.90	3.90	4.10	−	
	15				−	−	3.50	3.50	−	3.95	−	
	20				3.55	3.55	3.30	−	3.40	3.75	−	
	25				3.40	3.40	−	−	3.10	3.55	−	
	0			10	9.0	9.0	9.20	9.20	9.10	9.55	−	V
	5				−	−	−	−	−	9.25	−	
	10	−	−		8.85	8.85	9.00	9.00	9.00	9.15	−	
	15	−	−		−	−	−	−	−	9.05	−	
	20	−	−		8.70	8.70	8.40	8.40	8.60	8.90	−	
	25	−	−		8.60	8.60	−	−	8.30	8.75	−	
	0	−	−	15	14.0	14.0	14.20	14.20	14.10	14.55	−	V
	5	−	−		−	−	−	−	−	14.30	−	
	10	−	−		13.90	13.90	14.0	14.0	14.0	14.20	−	
	15	−	−		−	−	−	−	−	14.10	−	
	20	−	−		13.75	13.75	13.50	13.50	13.70	13.95	−	
	25	−	−		13.65	13.65	−	−	13.50	13.80	−	
Output Low (Sink) Current, I_{OL} Min.	−	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	−	mA
	−	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	−	
	−	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	−	
Input Current, I_{IN} Max.	−	0,18	0,18	18	±0.1	±0.1	±1	±1	−	±10^{-5}	±0.1	µA
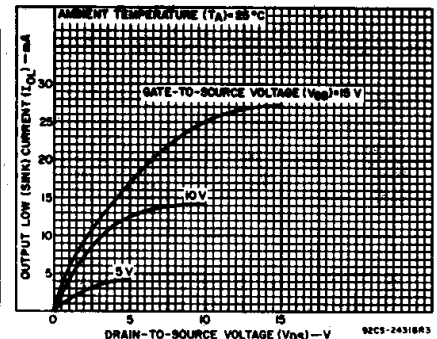
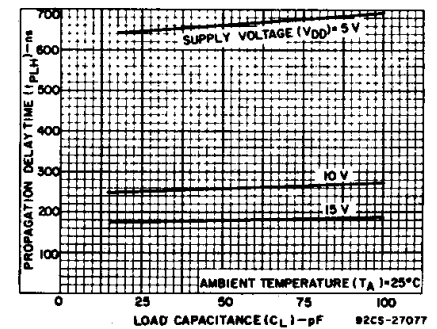Fig. 1 − Typical output low (sink) current characteristics.

Fig. 2 − Typical data-to-output, low-to-high-level propagation delay time as a function of load capacitance.
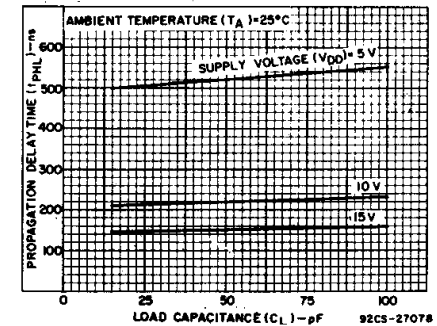

Fig. 3 − Typical data-to-output, high-to-low-level propagation delay time as a function of load capacitance.
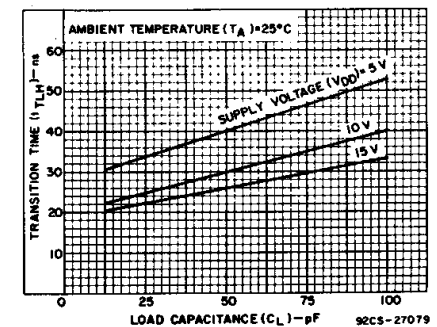

Fig. 4 − Typical low-to-high-level transition time as a function of load capacitance.

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25°C$, Input t_r, $t_f = 20$ ns, $C_L = 50$ pF, $R_L = 200$ kΩ

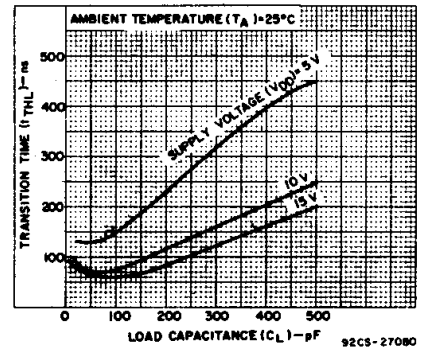| CHARACTERISTIC	Test Conditions V_{DD} Volts	LIMITS All Packages Min.	LIMITS All Packages Typ.	LIMITS All Packages Max.	UNITS
Propagation Delay Time: (Data) High-to-Low Level, t_{PHL}	5	–	520	1040	
	10	–	210	420	ns
	15	–	150	300	
Low-to-High Level, t_{PLH}	5	–	660	1320	
	10	–	260	520	ns
	15	–	180	360	
Propagation Delay Time: (BL) High-to-Low Level, t_{PHL}	5	–	350	700	
	10	–	175	350	ns
	15	–	125	250	
Low-to-High Level, t_{PLH}	5	–	400	800	
	10	–	175	350	ns
	15	–	150	300	
Propagation Delay Time: (LT) High-to-Low Level, t_{PHL}	5	–	250	500	
	10	–	125	250	ns
	15	–	85	170	
Low-to-High Level, t_{PLH}	5	–	150	300	
	10	–	75	150	ns
	15	–	50	100	
Transition Time: Low-to-High Level, t_{TLH}	5	–	40	80	
	10	–	30	60	ns
	15	–	25	50	
High-to-Low Level, t_{THL}	5	–	125	310	
	10	–	75	185	ns
	15	–	65	160	
Minimum Set-Up Time, t_S	5	150	75	–	
	10	70	35	–	ns
	15	40	20	–	
Minimum Hold Time, t_H	5	0	–75	–	
	10	0	–35	–	ns
	15	0	–20	–	
Strobe Pulse Width, t_W	5	400	200	–	
	10	160	80	–	ns
	15	100	50	–	
Input Capacitance, C_{IN}		–	5	7.5	pF

Fig. 5 – Typical high-to-low transition time as a function of load capacitance.
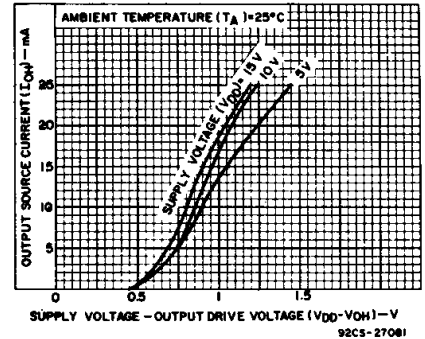

Fig. 6 – Typical voltage drop (V_{DD} to output) vs. output source current as a function of supply.
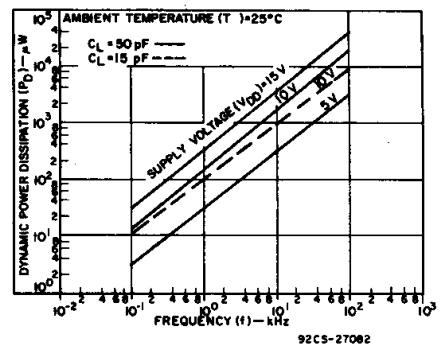

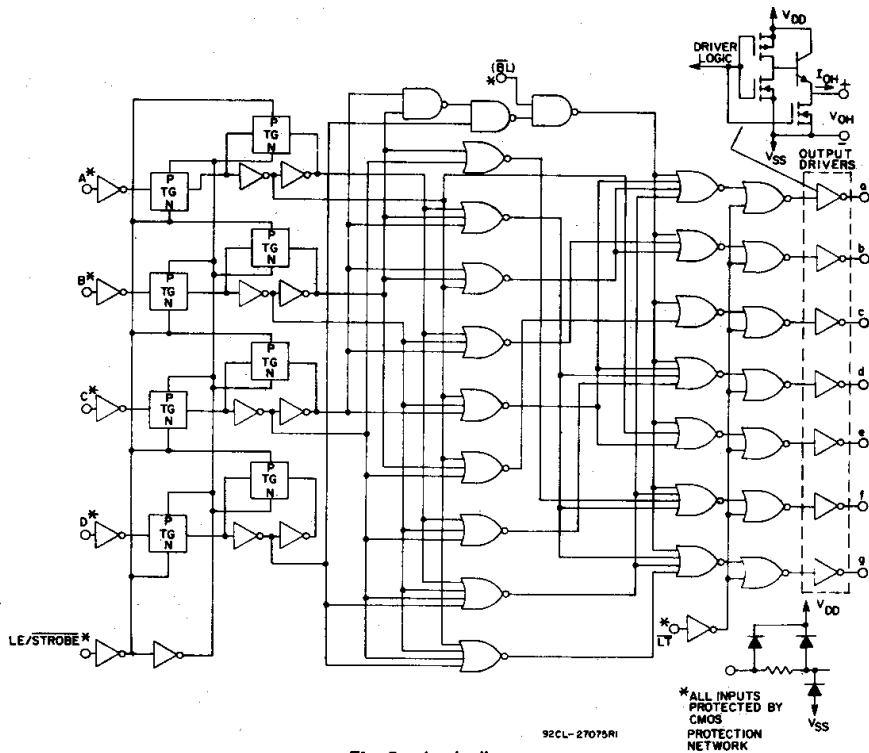*Fig. 7 – Typical dynamic power dissipation characteristics.*

3

COMMERCIAL CMOS HIGH VOLTAGE ICs

Fig. 8 – Logic diagram.

92CL-27075RI

*ALL INPUTS PROTECTED BY CMOS PROTECTION NETWORK

TRUTH TABLE

LE	BI	LT	D	C	B	A	a	b	c	d	e	f	g	Display
X	X	0	X	X	X	X	1	1	1	1	1	1	1	8
X	0	1	X	X	X	X	0	0	0	0	0	0	0	Blank
0	1	1	0	0	0	0	1	1	1	1	1	1	0	0
0	1	1	0	0	0	1	0	1	1	0	0	0	0	1
0	1	1	0	0	1	0	1	1	0	1	1	0	1	2
0	1	1	0	0	1	1	1	1	1	1	0	0	1	3
0	1	1	0	1	0	0	0	1	1	0	0	1	1	4
0	1	1	0	1	0	1	1	0	1	1	0	1	1	5
0	1	1	0	1	1	0	0	0	1	1	1	1	1	6
0	1	1	0	1	1	1	1	1	1	0	0	0	0	7
0	1	1	1	0	0	0	1	1	1	1	1	1	1	8
0	1	1	1	0	0	1	1	1	1	0	0	1	1	9
0	1	1	1	0	1	0	0	0	0	0	0	0	0	Blank
0	1	1	1	0	1	1	0	0	0	0	0	0	0	Blank
0	1	1	1	1	0	0	0	0	0	0	0	0	0	Blank
0	1	1	1	1	0	1	0	0	0	0	0	0	0	Blank
0	1	1	1	1	1	0	0	0	0	0	0	0	0	Blank
0	1	1	1	1	1	1	0	0	0	0	0	0	0	Blank
1	1	1	X	X	X	X	*							*

X ≡ Don't Care   * Depends on BCD code previously applied when LE = 0

Note: Display is blank for all illegal input codes (BCD > 1001).

TEST CIRCUITS

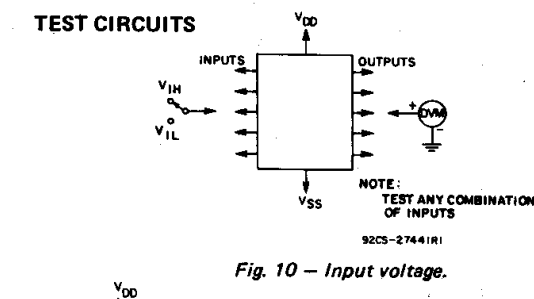Fig. 9 – Quiescent device current.

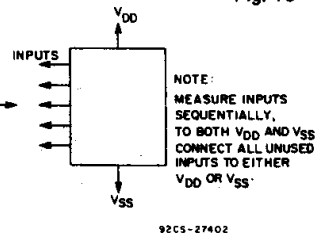92CS-2740IRI

NOTE: TEST ANY COMBINATION OF INPUTS

92CS-2744IRI

Fig. 10 – Input voltage.

NOTE: MEASURE INPUTS SEQUENTIALLY, TO BOTH V_DD AND V_SS CONNECT ALL UNUSED INPUTS TO EITHER V_DD OR V_SS.

92CS-27402

Fig. 11 – Input current.

t_r, t_f = 20 ns

92CS-25085

MEASURE OUTPUT d FOR t_{PLH}
MEASURE OUTPUT g FOR t_{PHL}

t_r = t_f = 20 ns

92CS-27088RI
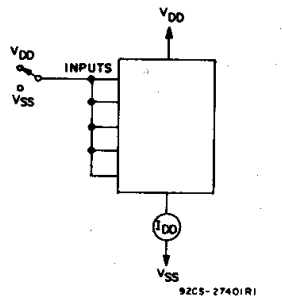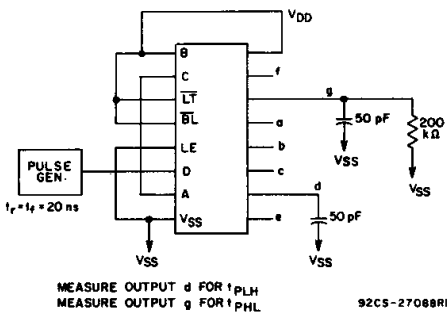
Fig. 12 – Data propagation delay.

t_r = t_f = 20 ns

92CS-27086RI
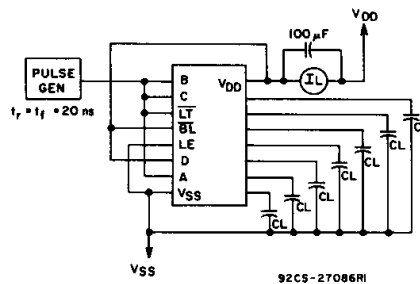
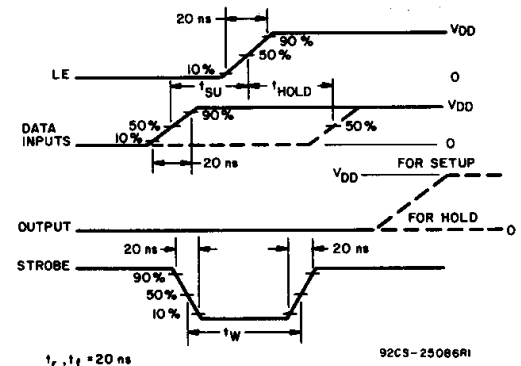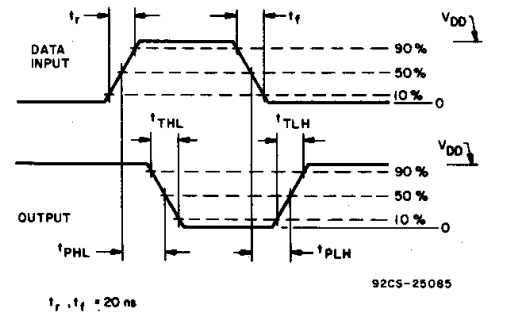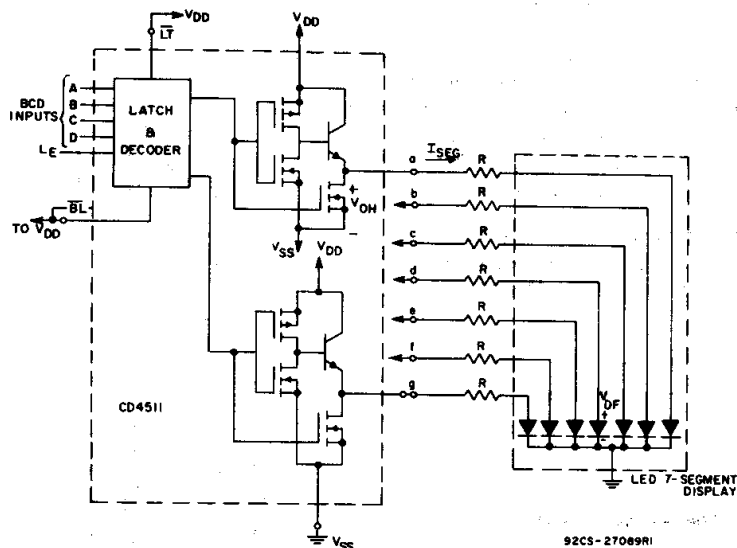Fig. 13 – Dynamic power dissipation.

t_r, t_f = 20 ns

92CS-25086RI

Fig. 14 – Dynamic waveforms.
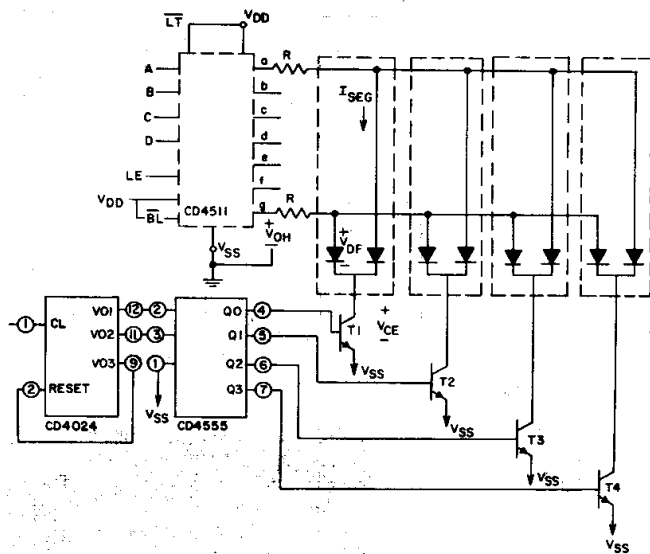
APPLICATIONS
Interfacing with Various Displays

Duty Cycle = 100%

$I_{SEG} = I_{DIODE_{AVG}} = 20$ mA at Luminous Intensity/Segment = 250 microcandles

$$R = \frac{V_{OH} - V_{DF}}{I_{SEG}}$$

Fig. 15 — Driving common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7740).

Multiplexing Scheme Showing 2 of 7 Segments Connected   92CM-27067RI

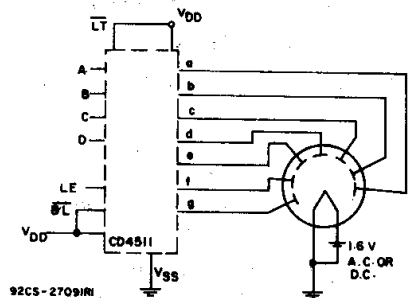Transistors $T_1 - T_4$ (RCA-2N3053 or 2N2102) have I_C Max. rating $> 7 \times I_{SEG}$

Duty Cycle = 25%

$I_{SEG} = [I_{DIODE_{AVG}}] \times 4$

$$R = \frac{(V_{OH} - V_{DF} - V_{CE})}{I_{SEG}}$$

All unused inputs on CD4555
are connected to V_{DD} or V_{SS}.

Fig. 18 — Multiplexing with common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7404 4 character display or 4 discrete Monosanto Man 3 displays).
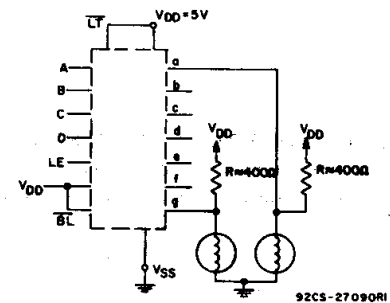

A medium-brightness intensity display can be obtained with low-voltage fluorescent displays such as the Tung-Sol Digivac S/G** Series.

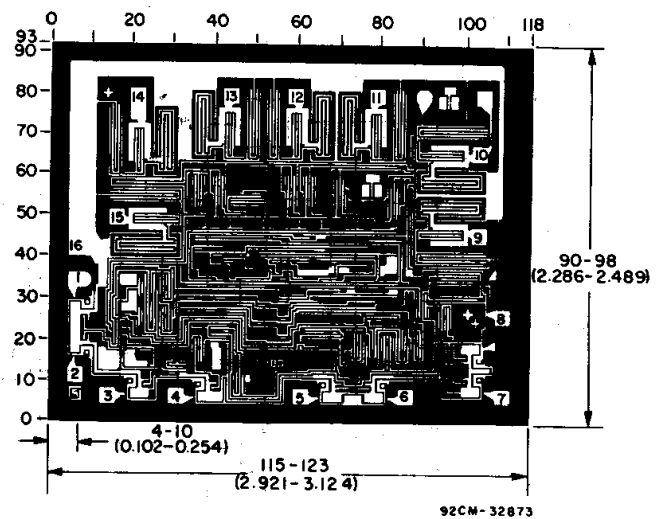**Trademark Tung-Sol Division Wagner Electric Co.

Fig. 16 — Driving low-voltage fluorescent displays.

2 of 7 Segments Shown Connected

Resistors R from V_{DD} to each 7-segment driver output are chosen to keep all Numitron segments slightly on and warm.

Fig. 17 — Driving incandescent displays (RCA Numitron DR2000 series displays).

Dimensions and pad layout for CD4511B chip.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4511BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4511BE	Samples
CD4511BEE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4511BE	Samples
CD4511BF	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4511BF	Samples
CD4511BF3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4511BF3A	Samples
CD4511BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4511B	Samples
CD4511BNSRG4	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4511B	Samples
CD4511BPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWG4	ACTIVE	TSSOP	PW	16	90	TBD	Call TI	Call TI	-55 to 125		Samples
CD4511BPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4511B, CD4511B-MIL :

● Catalog : CD4511B

● Military : CD4511B-MIL

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4511BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4511BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS
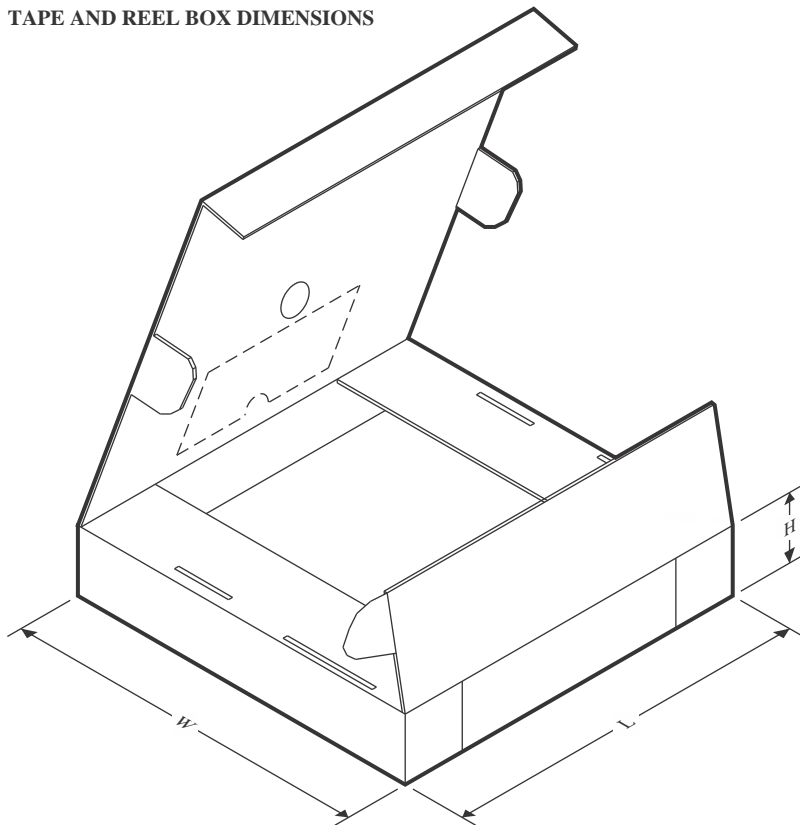
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4511BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4511BPWR	TSSOP	PW	16	2000	356.0	356.0	35.0

TUBE

T - Tube height

L - Tube length

W - Tube width

B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4511BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4511BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4511BEE4	N	PDIP	16	25	506	13.97	11230	4.32
CD4511BEE4	N	PDIP	16	25	506	13.97	11230	4.32
CD4511BPW	PW	TSSOP	16	90	530	10.2	3600	3.5

C

SEATING PLANE

0.1 C

8.2
7.4 TYP

A

PIN 1 ID
AREA

14X 1.27

1

16

10.4
10.0
NOTE 3

2X
8.89

8

9

16X 0.51
0.35

B

5.4
5.2
NOTE 4

0.25 (M) C A B

2.00 MAX

SEE DETAIL A

0.15 TYP

0.25

GAGE PLANE

0.3
0.1

0° - 10°

1.05
0.55
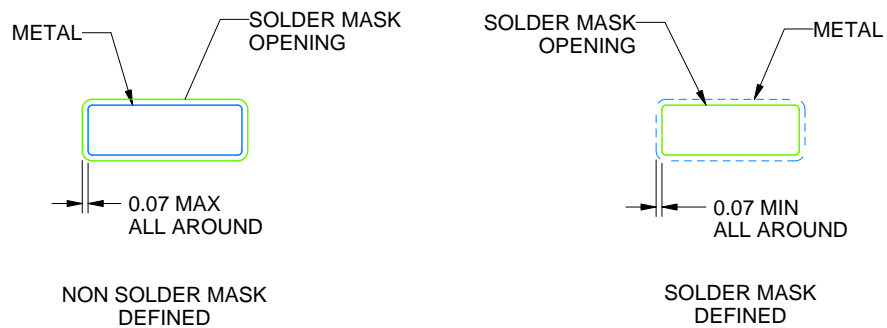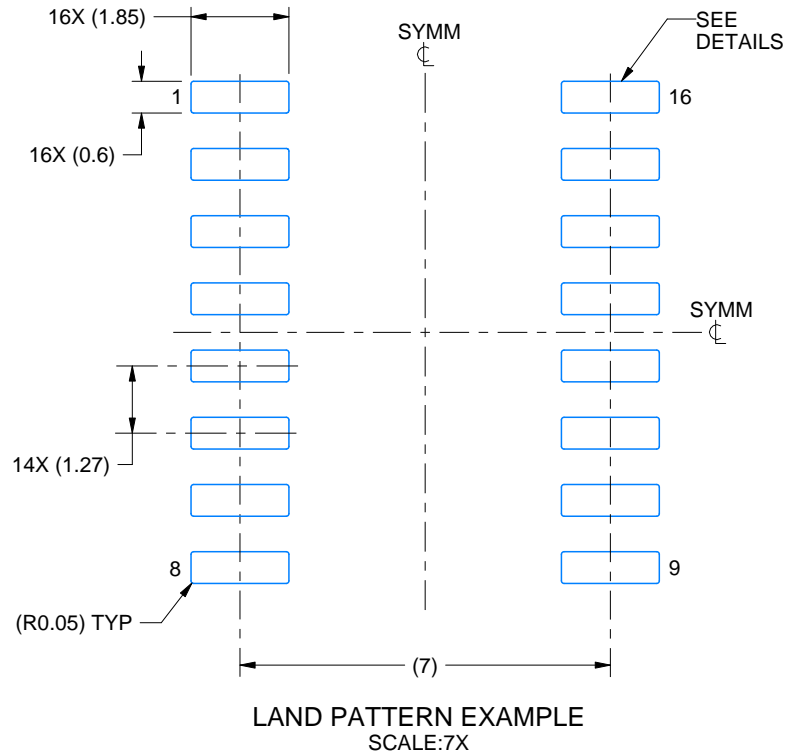
(1.25)

DETAIL A
TYPICAL
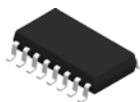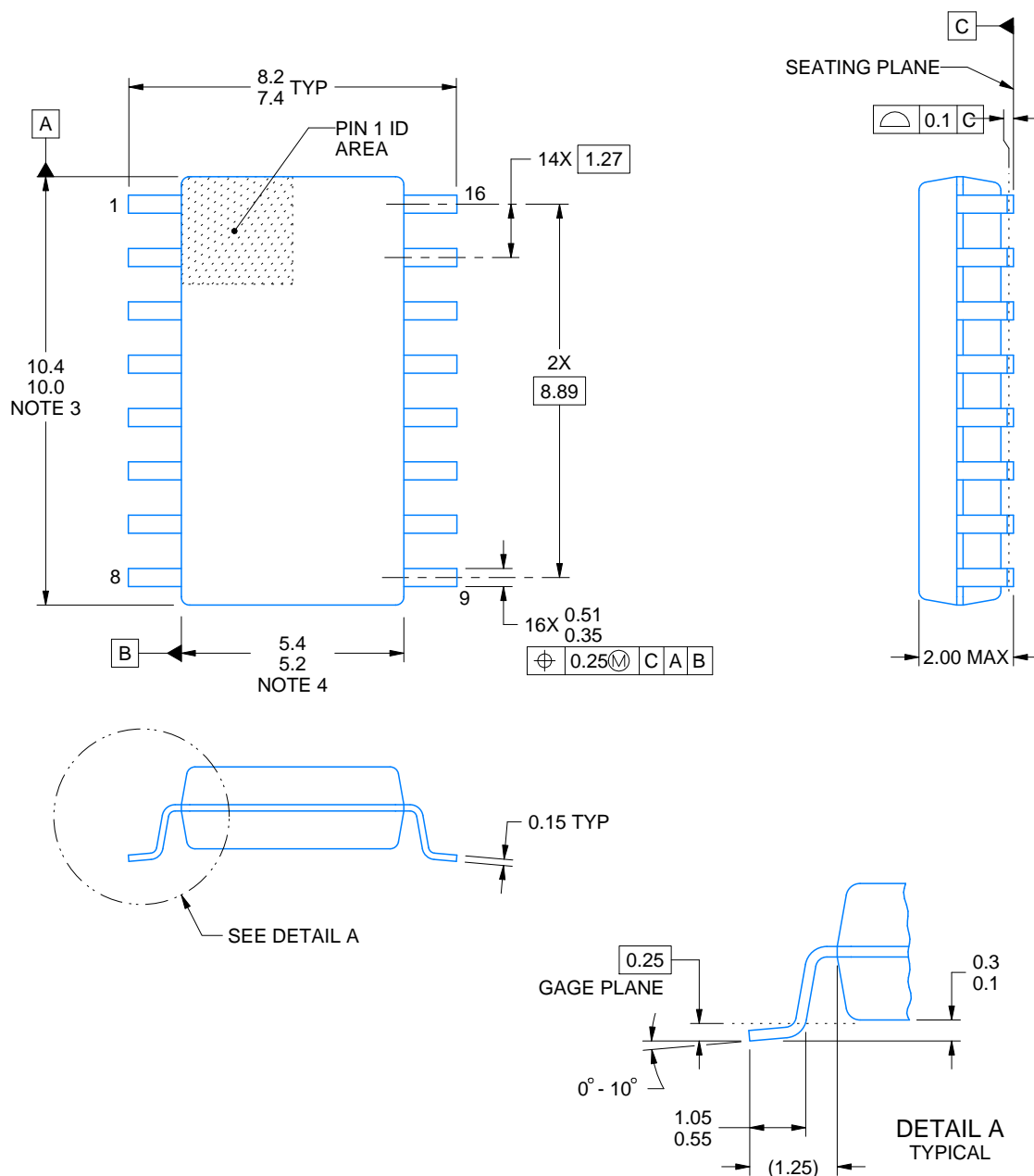
4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

16X (1.85)

SYMM

SEE
DETAILS

1

16

16X (0.6)

SYMM

14X (1.27)

8

9

(R0.05) TYP

(7)

LAND PATTERN EXAMPLE
SCALE:7X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL

0.07 MAX
ALL AROUND

0.07 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A   12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

16X (1.85)

SYMM
℄

1

16X (0.6)

16

SYMM
℄

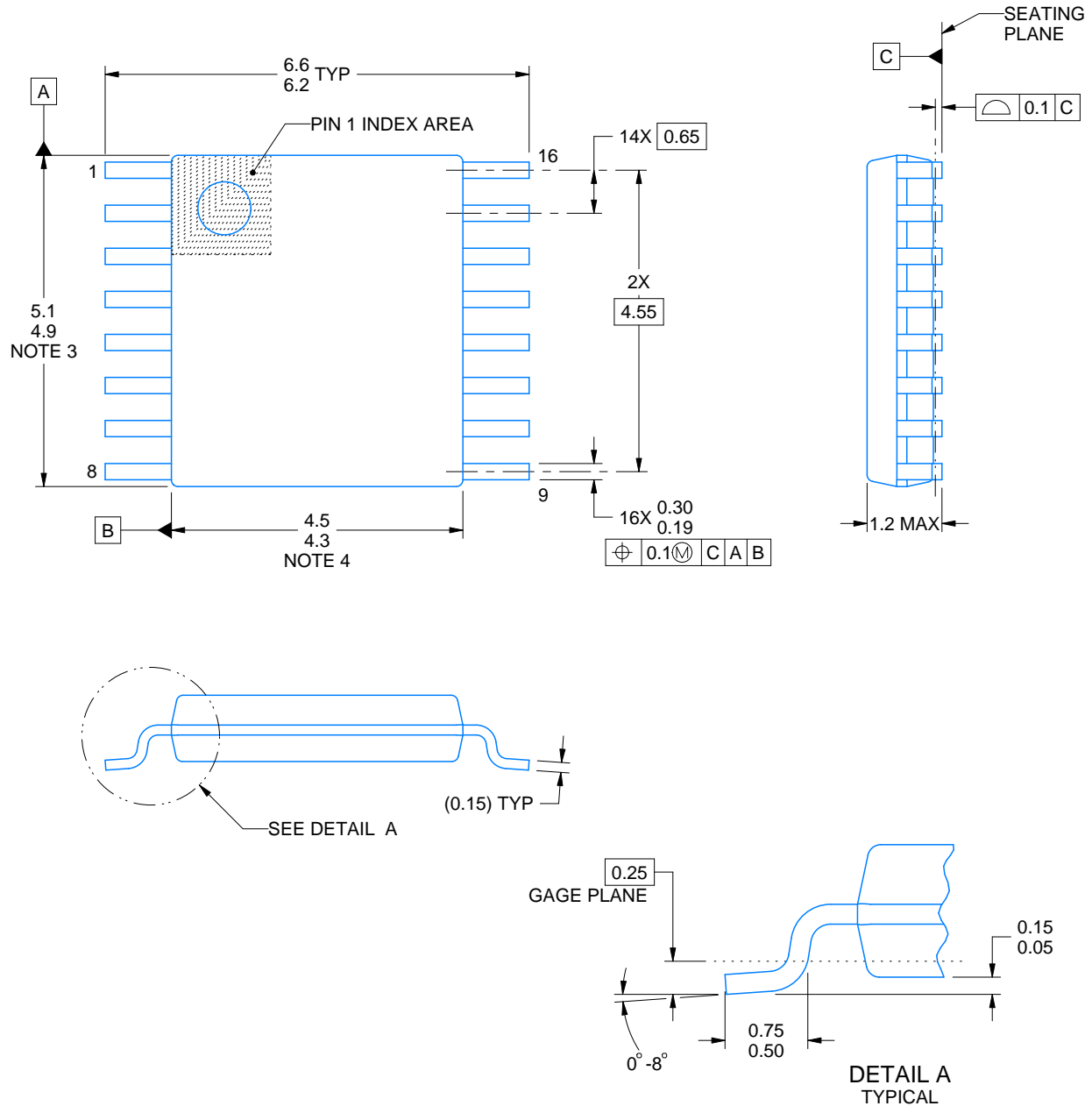14X (1.27)

8

9

(R0.05) TYP

(7)
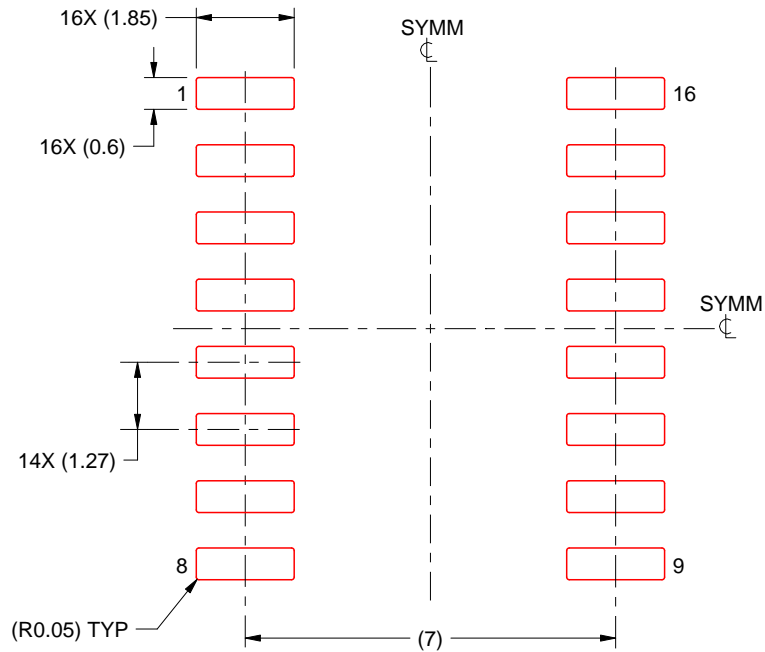
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A   12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
8. Board assembly site may have different recommendations for stencil design.
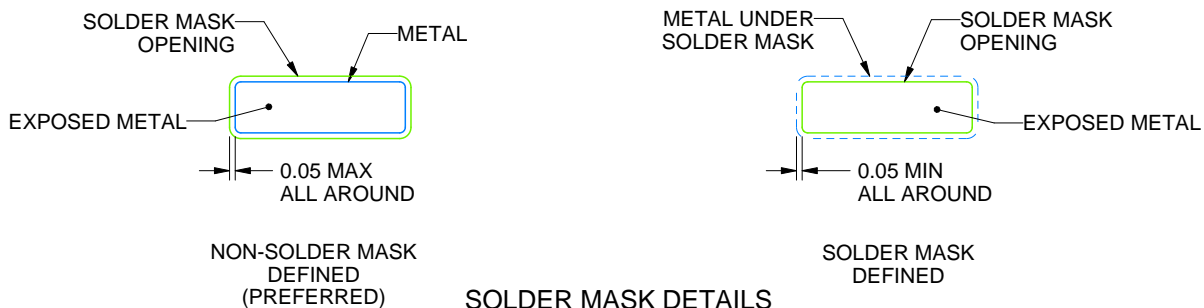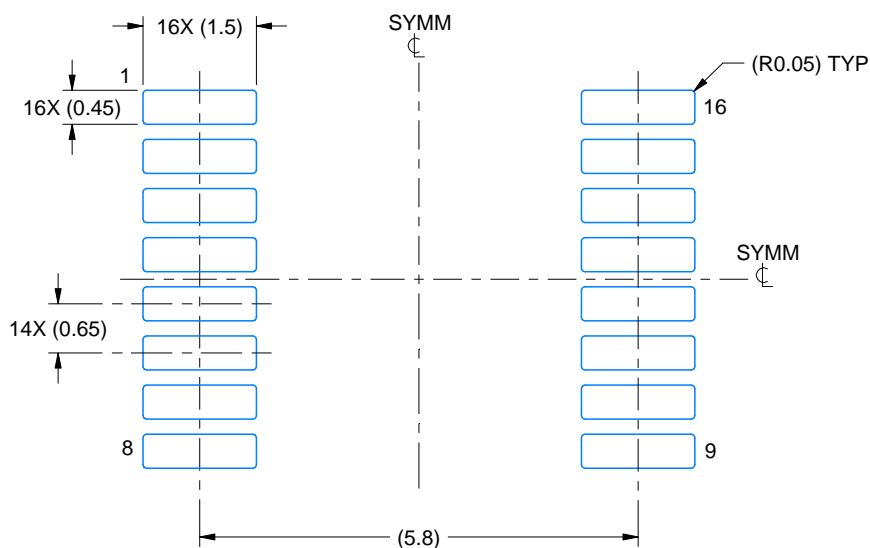
4220204/A   02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.05 MAX
ALL AROUND

NON-SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220204/A   02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

PW0016A

16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)
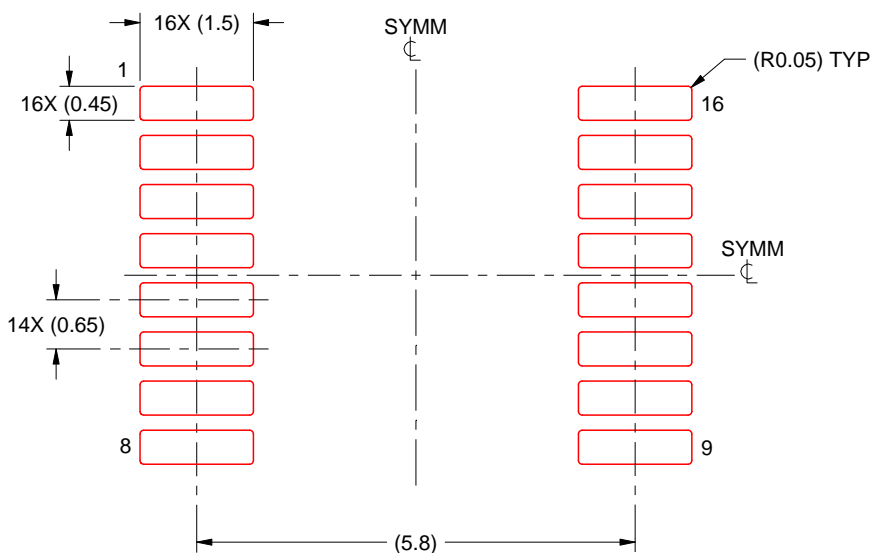
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
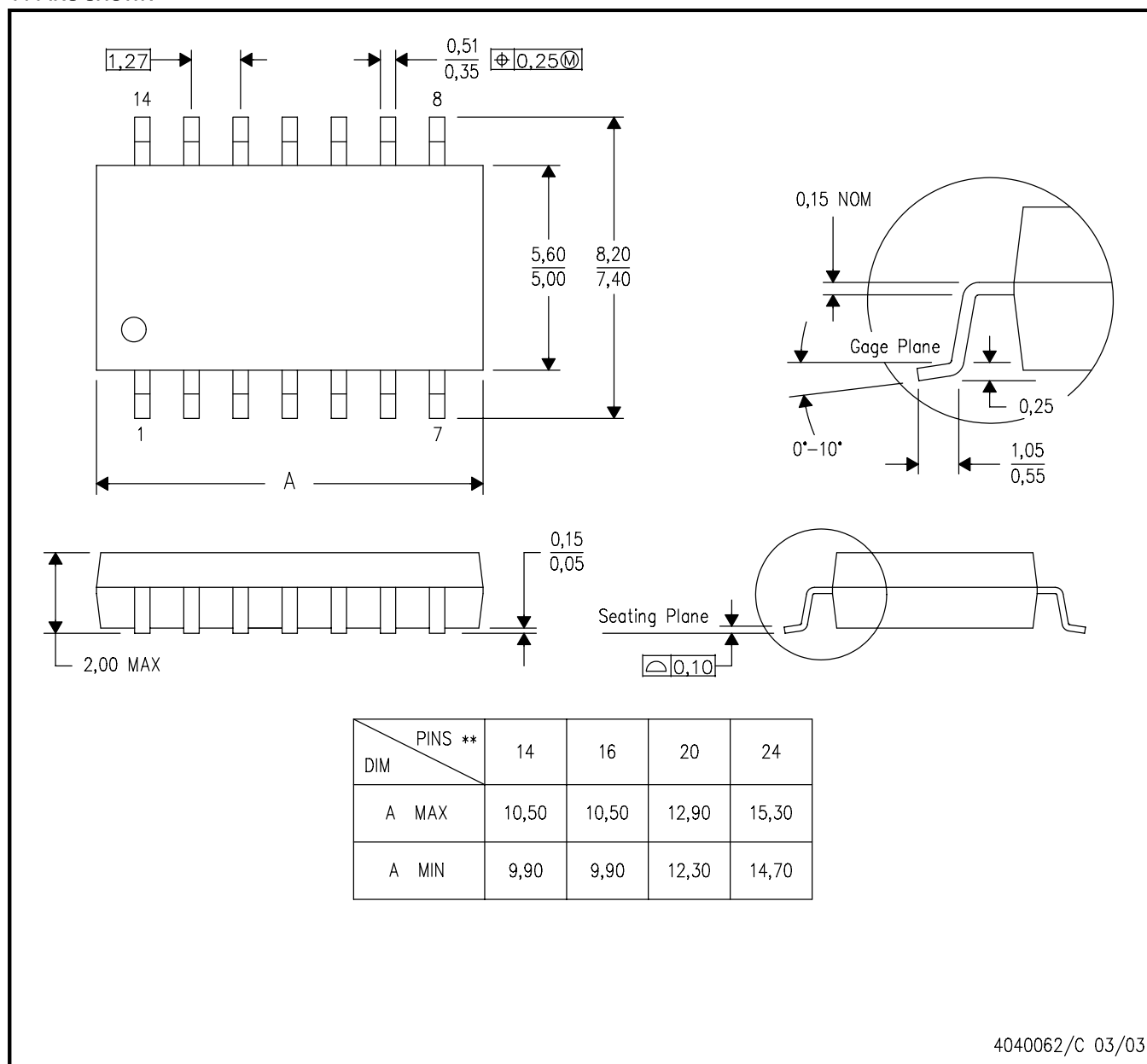SCALE: 10X

4220204/A   02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

NS (R-PDSO-G**)   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM / PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

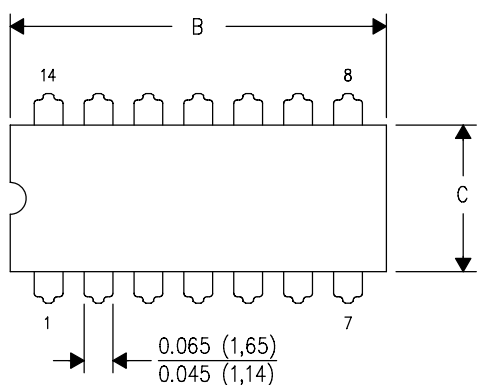4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.
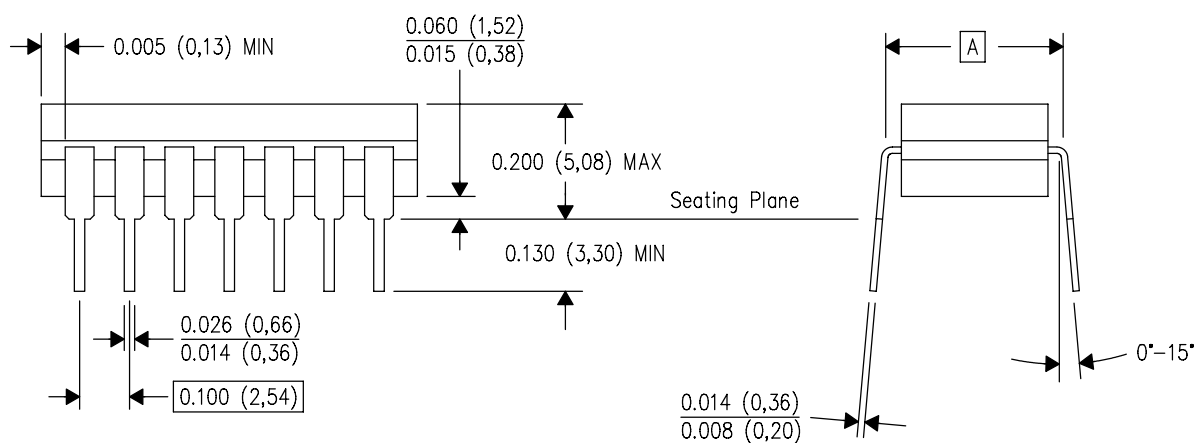
J (R−GDIP−T**)   CERAMIC DUAL IN−LINE PACKAGE
14 LEADS SHOWN

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

0.065 (1,65)
0.045 (1,14)

1   7

C

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)
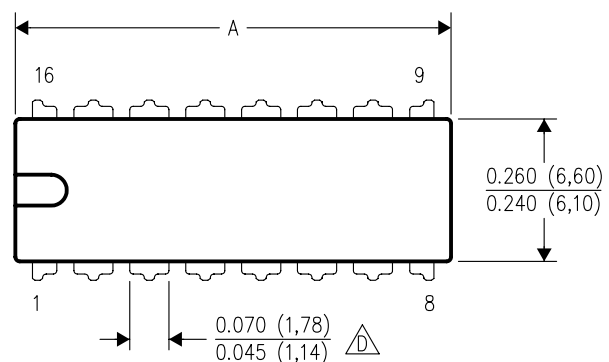
A

0°−15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
          C. This package is hermetically sealed with a ceramic lid using glass frit.
          D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
          E. Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

N (R−PDIP−T**)

16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
△C MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) △D

0.045 (1,14)
0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
      △C.   Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
      △D.   The 20 pin end lead shoulder width is a vendor option, either half or full width.

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